



LEOCO CORPORATION		PRODUCT SPECIFICATION	No.	S-96-6740	Rev	5
Item	Description (内容)	Test Method & Condition (测试方法与条件)	Requirement (需求)			
4-3	Contact removal Force (端子拔出力)	Crimped contact mounted in a housing shall be pulled in an alignment at a constant speed of 25 mm / minute.	3.0 Kgf min.			
4-4	Post Retention Force (保持力)	The end of a post shall be pushed in a perpendicular to base housing at a constant speed of 25 mm / minute.	1.0 Kgf min.			
4-5	Insertion Force (PIN 插入力)	Using 1.14mm square pin at a constant speed 25 mm / minute.	0.45 Kgf max.			
4-6	Withdrawal Force (PIN 拔出力)	Using 1.14mm square pin at a constant speed 25 mm / minute.	0.15 Kgf min.			
4-7	Mating and unmating force (only 4 position) (公母配合的插拔力)	Two mating connectors shall be fully mated or coupled at a rated specified.	See parameters 6.			
4-8	Durability (耐久性)	It should be tested in accordance with method EIA-364-09. Connector shall be subjected to 30 cycles of insertion and withdrawal	No defects. Contact resistance shall be 20 mΩ max.			
5. Environmental Performance (环境特性) :						
Item	Description (内容)	Test Method & Condition (测试方法与条件)	Requirement (需求)			
5-1	Humidity (耐湿性)	The unmated connector shall be tested in accordance with method EIA6364-31. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours.	NO damage. Contact resistance less Than twice of initial. Insulation resistance: to paragraph. 3-2. Dielectric withstand ing voltage: to paragraph 3-3			
5-2	Salt Spray (盐雾试验)	Connector shall be tested in accordance with method EIA-364-26. Temperature: 35±2 °C Density: 5 % in weight. Period: 48 hours.	NO damage. Contact resistance less than twice of initial.			
5-3	Solderability (着锡性)	Connector termination ends shall be checked for solderability in accordance with method EIA-364-252. Solder temperature: 260±5 °C Immersion period: 5±0.5 sec.	NO damage. Minimum: 95 % of immersed area.			

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Item	Description (内容)	Test Method & Condition (测试方法与条件)	Requirement (需求)
5-4	Resistance to Soldering Heat (附着耐热性)	Specimen shall be mounted on PCB. Solder temperature: 260±5 °C Immersion period: 5±0.5 sec.	NO damage and deformation.

6. Mating force and unmating force : Unit : Kgf

Number of circuits	Mating force(max.)	Unmating force (min.)		
	Initial	Initial	6 <sup>th</sup>	30th
02	1.8	0.25	0.15	0.08
04	2.6	0.5	0.50	0.15
06	4.10	0.8	0.85	0.33
08	5.50	1.2	1.30	0.62
10	6.80	1.6	1.85	1.00
12	8.30	2.0	2.20	1.18
14	9.70	2.4	2.65	1.47
16	11.00	2.8	3.10	1.75
18	12.50	3.2	3.30	1.90
20	13.80	3.6	3.50	2.05
22	15.20	4.1	3.75	2.25
24	16.50	4.6	4.05	2.39

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